

# Product Specification

## PE613010

UltraCMOS<sup>®</sup> SPST Tuning Control Switch, 100–3000 MHz

#### Features



- Very low on-resistance of 1.2Ω
- Low insertion 655
  - 0.20 dB @ 900 MHz
  - 0.40 dB @ 1900 MHz
- High power handling: 38 dBm (50Ω)
  - Wide power supply range (2.3V to 4.8V)
  - High ESD tolerance of 2 kV HBM
- Applications include:
  - Open and closed-loop tunable antennas for 2G/3G/4G
  - Tunable matching networks
  - Tunable filter networks
  - Bypassing applications
  - RFID readers

Figure 2. Package Type 10-lead  $2 \times 2 \times 0.55$  mm QFN



## Product Description

The PE613010 is an SPST tuning control switch based on Peregrine's UltraCMOS<sup>®</sup> technology. This highly versatile switch supports a wide variety of tuning circuit topologies with emphasis on impedance matching and aperture tuning applications. PE613010 features low onresistance and insertion loss from 100 to 3000 MHz.

PE613010 offers high RF power handling and ruggedness, while meeting challenging harmonic and linearity requirements enabled by Peregrine's HaRP<sup>™</sup> technology. With single-pin low voltage CMOS control, all decoding and biasing is integrated on-chip and no external bypassing or filtering components are required.

UltraCMOS tuning devices feature ease of use while delivering superior RF performance. With built-in bias voltage generation and ESD protection, tuning control switches provide a monolithically integrated tuning solution for demanding RF applications.



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#### Table 1. Electrical Specifications @ 25°C, V<sub>DD</sub> = 2.75V



#### Figure 3. Pin Configuration (Top View)



#### **Table 2. Pin Descriptions**

Pin #	Pin Name	Description
1	RF-	Negative RF Port <sup>1</sup>
2	RF–	Negative RF Port <sup>1</sup>
3	GND	Ground <sup>2</sup>
4	V <sub>DD</sub>	Power Supply Pin
5	GND	Ground <sup>2</sup>
6	GND	Ground <sup>2</sup>
7	V1	Switch control input, CMOS logit level
8	RF+	Positive RF Port <sup>1</sup>
9	RF+	Positive RF Port <sup>1</sup>
10	GND	Ground <sup>2</sup>
11	GND	Exposed Ground Reddle <sup>2</sup>

Notes: 1. Multiple RF pins are provided for hexibility. They can be tied together for optimal RF performance, or used inflividually (leave unused pin floating).
2. For optimal performance, incompleted tying Pins 3. 5, 6, 10, 11 together on PCB.

#### Moisture Sensitivity Level

The Moisture consitivity Level rating for the PE613010 in the 10-lead  $2 \times 2 \times 0.55$  mm QFN package is MSL1.

### Table 3. Truth Table

State	V1
Switch OFF	0
Switch ON	1

#### **Table 4. Operating Ranges**

Parameter	Min	Тур	Max	Unit
V <sub>DD</sub> Supply Voltage	2.30	2.75	5.50	V
$I_{DD}$ Power Supply Current (V <sub>DD</sub> = 2.75V, 25°C)		140	-	μA
V <sub>IH</sub> Control Voltage High	12	1.8	3.1	V
VIL Control Voltage Low	0	0	0.57	V
Peak Operating RF Voltage <sup>1,2</sup> 100 MHz–3 GHz	2		25 <sup>3</sup>	Vpk
Top Operating Temperature Range	-40	+25	+85	°C

Notes: 1. Between all RF ports, anotrop RF ports to GND.
2. Pulsed RF input duty cycle of 50% and 4620 μs, measured per 3GPP TS 45.005.
3. RF input power of %8 dBm (50Ω, SW<sub>ON</sub>) and 32 dBm (50Ω, SW<sub>OFF</sub>).

### Table 5. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Unit
VD	Supply Voltage	-0.3	5.5	V
VCTR	Digital Input Voltage (V1)	-0.3	3.6	V
T <sub>ST</sub>	Storage Temperature Range	-65	+150	°C
V <sub>ESD,HBM</sub>	H3M ESD Voltage, All Pins*		2000	V
	Symbol VDb VCTH IST VESD,HBM	Symbol         Parameter/Conditions           Vpb         Supply Voltage           VcrR         Digital Input Voltage (V1)           Tst         Storage Temperature Range           V <sub>ESD,HBM</sub> HBM ESD Voltage, All Pins*	SymbolParameter/ConditionsMinV_DbSupply Vehage-0.3V_CTRDigital Inpat Voltage (V1)-0.3I_STStorage Temperature Range-65V_ESD,HEMHBM ESD Voltage, All Pins*	SymbolParameter/ConditionsMinMaxV_DbSupply Veltage-0.35.5V_CTRDigital Input Voltage (V1)-0.33.6T_STStorage Temperature Range-65+150V_ESD,HEMHeM ESD Voltage, All Pins*2000

Note: \* Human Body Model (MIL\_STD 883 Method 3015.7).

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

#### **Electrostatic Discharge (ESD) Precautions**

When handling this UltraCMOS device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

#### Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS devices are immune to latch-up.



#### Equivalent Circuit Model Description

The Equivalent Circuit Model includes all parasitic elements and is accurate in switch on and switch off states, reflecting physical circuit behavior accurately and providing very close correlation to measured data. It can easily be used in circuit simulation programs.

C<sub>s</sub> represents switch core capacitance between RF+ and RF- ports in the SW<sub>OFF</sub> state. The parameter R<sub>S</sub> represents the Equivalent Series Resistance (ESR) of the switch core.

Parasitic inductance due to circuit and package is modeled as L<sub>S</sub>. C<sub>P</sub> represents the circuit and package parasitics from RF ports to GND.

R<sub>sw</sub> RF+ C Cc R<sub>P</sub>

#### Table 6. Equivalent Circuit Model Parameters

nodeled as $L_s$ . $C_P$ represents the circuit and	Parameter	Equation (SW=0 for OPE and SW=1 for ON)	Unit
ackage parasitics from RF ports to GND.	Cs		pF
	CP	0.65	pF
	Paw	it SW == 1 then 1.2 else 100e3	Ω
		6	Ω
		0.35	nH
X	$\langle \langle \langle \rangle \rangle$	2 ×	
$\sim$	<b>΄.</b> λ΄		
	$\mathbf{X}$		
A. V.			
	•		
$O_{I_{2}} \rightarrow I$			
<b>X</b> `			
$\cap$			
7			
•			

## Figure 4. Equivalent Circuit Model Schematic



#### **Evaluation Board**

The 101-0738 Evaluation Board (EVB) was designed for accurate measurement of the tuning switch impedance and loss using 2 Port Series (J4, J5) configuration. Three calibration standards are provided. The open (J2) and short (J1) standards (104 ps delay) are used for performing port extensions and accounting for electrical length and transmission line loss. The Thru (J8, J10) standard can be used to estimate PCB transmission line loss for scalar de-embedding.

The board consists of a 4 layer stack with 2 outer layers made of Rogers 4350B ( $\varepsilon_r = 3.48$ ) and 2 inner layers of FR4 ( $\varepsilon_r = 4.80$ ). The total thickness of this board is 62 mils (1.57 mm). The inner layers provide a ground plane for the NOT REPERENT transmission lines. Each transmission line is designed using a coplanar waveguide with

Figure 5. Evaluation Board



PRT-08405



#### Figure 6. Evaluation Board Schematic





#### Figure 6. Package Drawing

10-lead  $2 \times 2 \times 0.55$  mm





#### Figure 8. Tape and Reel Specifications



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